

## JAPANESE PATENT OFFICE

## PATENT JOURNAL

KOKAI PATENT APPLICATION NO. HEI 7[1995]-307437

## Technical Disclosure Section

Int. Cl. <sup>6</sup> :	H 01 L	25/065 25/07 25/18
	H 01 L	25/08
Application No.:	Hei 6[1994]-120493	
Application Date:	May 10, 1994	
Publication Date:	November 21, 1995	
No. of Claims:	2 (Total of 4 pages; FD)	
Examination Request:	Not requested	

## HIGH-DENSITY MOUNTING METHOD

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[There are no amendments to this patent.]

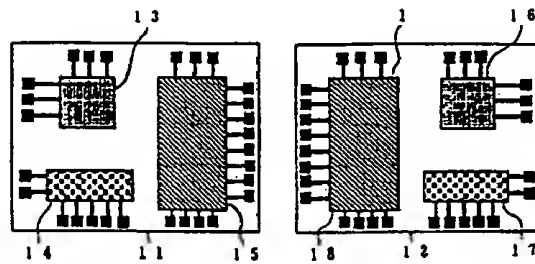
## Abstract

### Purpose

To mount semiconductor elements with high mounting density.

### Constitution

The pin arrangements of semiconductor elements 11 and 12 are such that, when said semiconductor elements are stacked [facing each other], of these semiconductor elements occupy the same position.



## Claims

1. A high-density mounting method in which multiple semiconductor elements are mounted, characterized in that the wiring of each of the aforementioned multiple semiconductor elements is formed such that, when stacked [facing each other], the pins of the aforementioned multiple semiconductor elements will occupy the same positions.

2. The high-density mounting method of Claim 1, wherein the  
aformentioned multiple semiconductor elements are on a substrate.

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